L	Hits	Search Text	DB	Time stamp
Number	129	(partial adj processing or selective adj	USPAT;	2004/11/04
	123	processing) and semiconductor adj wafer	US-PGPUB;	16:19
			EPO; JPO;	
		,	DERWENT;	i
			IBM_TDB	
-	3		USPAT;	2004/06/23
		selective adj processing) and	US-PGPUB;	10:47
		semiconductor adj wafer)	EPO; JPO; DERWENT;	
			IBM TDB	
	96	processing adj chuck	USPAT;	2004/06/23
	·		US-PGPUB;	10:46
İ		•	EPO; JPO;	i
			DERWENT;	
	17	o-ring and (processing adj chuck)	IBM_TDB USPAT;	2004/06/22
_	1/	o-ring and (processing adj chuck)	USPAT; US-PGPUB;	2004/06/23
			EPO; JPO;	10.55
1			DERWENT;	
			IBM_TDB	
-	15	partial adj wafer adj processing	USPAT;	2004/06/23
			US-PGPUB;	11:04
			EPO; JPO; DERWENT;	·
			IBM TDB	
_	o	mobil adj chamber and semiconductor adj	USPAT;	2004/06/23
		wafer	US-PGPUB;	11:04
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	2004/06/02
-	1	mobile adj chamber and semiconductor adj wafer	USPAT; US-PGPUB;	2004/06/23
		walei	EPO; JPO;	11.05
			DERWENT;	
			IBM_TDB	
-	8	micro adj chamber and semiconductor adj	USPAT;	2004/06/23
		wafer	US-PGPUB;	11:07
			EPO; JPO; DERWENT;	
			IBM TDB	
_	435	(451/39).CCLS.	USPAT;	2004/06/23
	İ		US-PGPUB;	11:10
			EPO; JPO;	
		•	DERWENT;	
_	794	(118/720).CCLS.	IBM_TDB USPAT;	2004/06/23
	',54	(110),20),000.	US-PGPUB;	11:34
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	0004/06/00
_	10	4676193.URPN.	USPĀT	2004/06/23
1_	0	"partically covering the substrate"	USPAT;	11:26 2004/06/23
		partitionally covering the substrate	US-PGPUB;	11:34
			EPO; JPO;	
			DERWENT;	1
	_		IBM_TDB	0004/06/00
_	0	"partially covering the substrate"	USPAT;	2004/06/23
			US-PGPUB; EPO; JPO;	11.34
			DERWENT;	
			IBM TDB	
_	0	"partlly covered substrate"	USPAT;	2004/06/23
			US-PGPUB;	11:36
-			EPO; JPO;	
			DERWENT; IBM TDB	
	<u></u>	<u> </u>	1 1011 100	1

				0004/05/55
-	10	"partially covered substrate"	USPAT;	2004/06/23
			US-PGPUB; EPO; JPO;	11:37
			DERWENT;	
			IBM TDB	
-	2	micro adj process adj chamber	USPAT;	2004/06/23
			US-PGPUB;	11:47
			EPO; JPO;	ļ
		,	DERWENT;	
	_	5000000	IBM_TDB	
-	6	5997963.URPN.	USPAT	2004/06/23
l _	5	(micro adj process adj chamber or micro	USPAT;	11:39 2004/06/23
	,	adj chamber) and (air adj bearing or gas	US-PGPUB;	11:48
		adj bearing)	EPO; JPO;	
]		3	DERWENT;	
İ			IBM_TDB	
-	6	5997963.uref.	USPAT;	2004/06/23
			US-PGPUB;	11:48
			EPO; JPO;	
			DERWENT; IBM TDB	
_	12	("4704348" "4801352" "5025284"	USPAT	2004/06/23
		"5087927" "5103102" "5559584"		11:50
		"5877843" "5973764" "5997963"		
		"6208406" "6313953" "6538716"		
		"2002/0145711" "2003/0006380").PN.		0004/05/55
ļ -	7	("4778745" "5428442" "5838951"	USPAT	2004/06/23
		"5851848" "5943551" "6016358"		12:03
	0	"6028664").PN. 6216055.URPN.	USPAT	2004/06/23
⁻ . !		0210033.URFN.	OSTAI	12:07
_	448	(differential adj pumped or	USPAT;	2004/06/23
		differentially adj pumped or differential	US-PGPUB;	12:12
		adj pumping) and portion and (wafer or	EPO; JPO;	
1		substrate) and (process or processing)	DERWENT;	
			IBM_TDB	0004/06/00
-	211		USPAT;	2004/06/23
		pumped or differentially adj pumped or differential adj pumping) and portion and	US-PGPUB; EPO; JPO;	12:23
		(wafer or substrate) and (process or	DERWENT;	
		processing))	IBM TDB	
_	921	noji.in.	USPAT;	2004/06/23
			US-PGPUB;	12:23
1			EPO; JPO;	
1			DERWENT;	
l _	78	chamber and noticin	IBM_TDB USPAT;	2004/06/23
-	/8	chamber and noji.in.	US-PGPUB;	12:30
			EPO; JPO;	
1		·	DERWENT;	
1	1		IBM_TDB .	
-	969	ebara adj corporation.as.	USPAT;	2004/06/23
			US-PGPUB;	12:31
			EPO; JPO; DERWENT;	
			IBM TDB	
-	2	((differential adj pumped or	USPAT;	2004/06/23
	1	differentially adj pumped or differential	US-PGPUB;	12:31
		adj pumping) and portion and (wafer or	EPO; JPO;	
		substrate) and (process or processing))	DERWENT;	
	350	and (ebara adj corporation.as.)	IBM_TDB USPAT;	2004/11/04
-	750	(438/758).CCLS.	US-PGPUB;	16:23
			EPO; JPO;	-3.23
			DERWENT;]
1	1		IBM_TDB	
-	42	o-ring and ((438/758).CCLS.)	USPAT;	2004/11/04
			US-PGPUB;	16:20
	1		EPO; JPO;	
	1		DERWENT; IBM TDB	
1	i	I .	I TOM IND	1

			T	
-	149	(438/765).CCLS.	USPAT;	2004/11/04
			US-PGPUB;	16:26
			EPO; JPO;	1
			DERWENT;	1
	_	l	IBM_TDB	1 / /
-	38	mobile adj workpiece	USPAT;	2004/11/04
			US-PGPUB;	16:30
			EPO; JPO;	
			DERWENT;	
	-		IBM_TDB	1
-	0	minature adj process adj chamber	USPAT;	2004/11/04
			US-PGPUB;	16:31
,			EPO; JPO;	
			DERWENT;	
			IBM TDB	
l –	2	micro adj process adj chamber	USPĀT;	2004/11/04
			US-PGPUB;	16:40
			EPO; JPO;	
			DERWENT;	
		·	IBM TDB	
_	2	("6764386").PN.	USPĀT;	2004/11/04
		,	US-PGPUB;	16:43
			EPO; JPO;	
			DERWENT;	
	,		IBM TDB	
_	6	("4987286" "5202008" "5898179"	USPAT	2004/11/04
		"5921560" "5931721" "6056632"		16:41
		"2001/0055937" "2004/0009738"		
		"2004/0029494").PN.		
	6	· · · · · · · · · · · · · · · · · · ·	USPAT;	2004/11/04
~	ا ۳	("20010055937") OF ("20040009738") OF	US-PGPUB;	16:43
		(ZUUHUUZHHH)).FN.		10.73
1			EPO; JPO;	
1			DERWENT;	1
1		/UA00700/U UE000000 UE0001707	IBM_TDB	2004/11/04
-	6	("4987286" "5202008" "5898179"	USPAT	2004/11/04
1		"5921560" "5931721" "6056632"		16:44
		"2001/0055937" "2004/0009738"		
		"2004/0029494").PN.	IIG D. m	2004/11/04
_	0	6764386.URPN.	USPAT	2004/11/04
		(440 / 700)		16:45
-	927	(118/729).CCLS.	USPAT;	2004/11/04
			US-PGPUB;	17:17
			EPO; JPO;	
		·	DERWENT;	1
			IBM_TDB	
-	2958	(427/248.1).CCLS.	USPAT;	2004/11/04
			US-PGPUB;	17:18
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
_	117	o-ring and ((427/248.1).CCLS.)	USPAT;	2004/11/04
	1	·	US-PGPUB;	17:23
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
-	750	(438/758).CCLS.	USPAT;	2004/11/04
			US-PGPUB;	17:22
}		'	EPO; JPO;	
			DERWENT;	
			IBM TDB	
-	42	o-ring and ((438/758).CCLS.)	USPAT;	2004/11/04
			US-PGPUB;	17:23
			EPO; JPO;	
]		DERWENT;	1
			IBM TDB	1
	1	,		1